



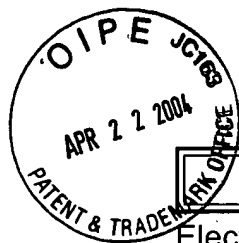
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Electronic Filing System (EFS) Data
Electronic Patent Application Submission
USPTO Use Only

EFS ID: 59489
Application ID: 10026854
Title of Invention: ARTICLES FOR POLISHING
SEMICONDUCTOR SUBSTRATES
First Named Inventor: Shijian Li
Domestic/Foreign Application: Domestic Application
Filing Date: 2001-12-20
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Statement
Filing Type:
Confirmation number: 1816
Attorney Docket Number: AMAT/5765
Total Fees Authorized: 180.0
Payment Category: Deposit Account
Deposit Account Number: 200782
Deposit Account Name: Keith P Taboada
Access Code: ****
RAM Payment Status: RAM success
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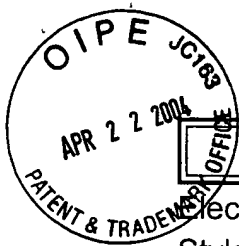
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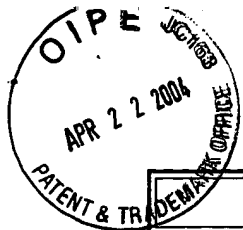
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Stylesheet Version v1.1.0

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<table border="1"><thead><tr><th>Submitted by:</th><th>Elec. Sign.</th><th>Sign. Capacity</th></tr></thead><tbody><tr><td>Keith P Taboada Registered Number: 45150</td><td>/Keith P Taboada/</td><td>Attorney</td></tr></tbody></table>			Submitted by:	Elec. Sign.	Sign. Capacity	Keith P Taboada Registered Number: 45150	/Keith P Taboada/	Attorney								
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<table><tr><td>Documents being submitted</td><td>Files</td></tr><tr><td>us-fee-sheet</td><td>APPM5765-usfees.xml</td></tr><tr><td></td><td>us-fee-sheet.xml</td></tr><tr><td></td><td>us-fee-sheet.dtd</td></tr><tr><td>us-ids</td><td>APPM5765-usidst.xml</td></tr><tr><td></td><td>us-ids.dtd</td></tr><tr><td></td><td>us-ids.xml</td></tr></table>			Documents being submitted	Files	us-fee-sheet	APPM5765-usfees.xml		us-fee-sheet.xml		us-fee-sheet.dtd	us-ids	APPM5765-usidst.xml		us-ids.dtd		us-ids.xml
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	us-ids.dtd															
	us-ids.xml															
Comments																

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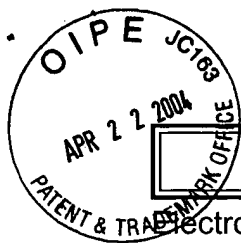
Electronic Version v08
Stylesheet Version v08.0

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Art Unit: 3723											
Examiner: Alvin JGrant											
TOTAL FEE AUTHORIZED \$180											
Patent fees are subject to annual revisions on or about October 1st of each year.											
BASIC FILING FEE											
<table border="1"><thead><tr><th>Fee Description</th><th>Fee Code</th><th>Amount \$</th><th>Fee Paid \$</th></tr></thead><tbody><tr><td>Submission Of Information Disclosure Stmt Fee</td><td>1806</td><td>180</td><td>180</td></tr></tbody></table>				Fee Description	Fee Code	Amount \$	Fee Paid \$	Submission Of Information Disclosure Stmt Fee	1806	180	180
Fee Description	Fee Code	Amount \$	Fee Paid \$								
Submission Of Information Disclosure Stmt Fee	1806	180	180								
AUTHORIZED BILLING INFORMATION											
The commissioner is hereby authorized to charge indicated fees and credit any overpayments to:											
Deposit account number: 200782											
Access Code ****											
Deposit name: Moser Patterson and Sheridan LLP											
Deposit authorized name: Keith P Taboada											
Signature: /Keith P Taboada/											
Date (YYYYMMDD): 2004-04-22											

**FEE TRANSMITTAL**


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AUTHORIZED BILLING INFORMATION The commissioner is hereby authorized to charge indicated fees and credit any overpayments to: Deposit account number: 200782 Access Code ***** Deposit name: Moser Patterson and Sheridan LLP Deposit authorized name: Keith P Taboada Signature: /Keith P Taboada/ Date (YYYYMMDD): 2004-04-22									



ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18
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Title of Invention	ARTICLES FOR POLISHING SEMICONDUCTOR SUBSTRATES																										
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